

# S32V2xx Development Package 3.1.1

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# 1. Release Description

NXP Semiconductors is pleased to announce the release of the S32V2xx Development Package 3.1.1 for S32 Design Studio 3.1.

## 1.1. Release Content

- Support for wizards creating application and library projects for the S32V2xx processor family
- Support for wizard creating projects for S32V2xx from project examples
- Project examples for the S32V2xx processor family
- Integrated S32 SDK for S32V23x BETA 0.9.0 (Windows only)
- Integrated S32 SDK for S32V23x RTM 1.0.0 (Windows only)
- Integrated AMMCLIB SDKs for S32V234 version 1.1.15
- S32 Configuration Tool support
- S32 Debug Probe support
- PEMicro debugger support
- Lauterbach Trace32® support
- DDR Stress Test tool

## 2. What's New

### 2.1. Supported Devices

The package provides support for the following devices:

- S32V232
- S32V234

### 2.2. New Features

- Creating application and library projects.
- Creating projects for the shared and static Linux libraries.
- Creating projects from project examples.
- On-chip debugging with the S32 Debug Probe, PEMicro, and Lauterbach probes.

## 3. Installation and Licensing

The development package shall be installed on S32 Design Studio 3.1 using the **S32DS Extensions and Updates** wizard. Make sure to install the latest **S32 Design Studio Platform** and **S32 Design Studio Platform Tools** updates.

To install the development package:

1. Launch S32 Design Studio 3.1.
2. Choose **Help > S32DS Extensions and Updates** from the menu bar.
3. In the **S32DS Extensions and Updates** dialog box, select **S32V2xx development package** from the list and click **Install/Update**.
4. Review the information on the confirmation page and click **Next**.
5. Accept the license terms. Click **Finish** to complete the installation.

After the installation completes, S32 Design Studio 3.1 automatically prompts to be restarted.

You can download updates from the website manually to install the development package on the computer with no access to the internet:

1. Download the archive file.
  - a. Go to the [www.nxp.com](http://www.nxp.com) Product List page.
  - b. Select S32 Design Studio from the list.
  - c. Select the development package and click **Download Selected Files** to save the archive file in a local folder.
2. Install the development package.
  - a. Choose **Window > Preferences** from the menu bar.
  - b. In the **Preferences** dialog box, click **S32 Design Studio > S32DS Extensions and Updates**.
  - c. Click **Add...**
  - d. Click **Archive** in the **Add Site** dialog box.
  - e. Navigate to the directory with the downloaded ZIP file. Choose it and click **Open**, then click **OK**.
  - f. Choose **Help > S32DS Extensions and Updates** from the menu bar and continue the installation as usual.

## 4. Technical Support

The S32 Design Studio 3.1 general issues are tracked through the S32DS Public NXP Community space:

<https://community.nxp.com/community/s32/s32ds>

For confidential cases and cases which cannot be publicly shared on NXP Community please follow the steps described here:

<https://community.nxp.com/docs/DOC-329745>

## Appendix A. Known Issues and Workarounds

- **Build fails after attaching SDK to an existing project:** The SDK functionality is supported only for attaching an SDK using project creation wizard. Attaching SDK to an existing project results in incorrect handling of the startup and linker files.

**Workaround:** Right-click the project in the Project Explorer view, click Build Configurations Explorer on the context menu and exclude `startup_S32V_M4.S` from the build configurations. Then open the project properties, click **C/C++ Build > Settings > Standard S32DS C Linker > General** and replace the included linker script with the SDK one.



**How to Reach Us:**

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